

Xeon 2 Power 940nmInfrared Emitter LED

OSI5XNE3E1E

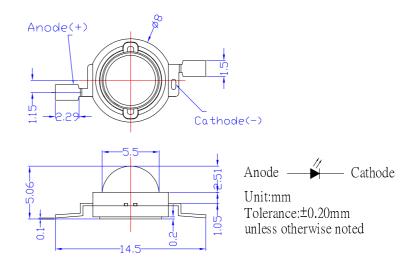
■Features

- · Highest luminous flux
- · Super energy efficiency
- Very long operating life
- · Superior ESD protection

Applications

- · Night Vision
- Camera
- Outdoor./Indoor applications

■Outline Dimension



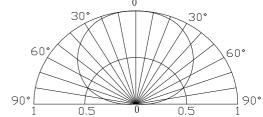
Directivity

■Absolute Maximum Rating

#Pulse width Max.10ms Duty ratio max 1/10

| Item | Symbol | Value | Unit |
|------------------------------|------------------|------------|------------------------|
| DC Forward Current | I_{F} | 1,000 | mA |
| Pulse Forward Current# | I_{FP} | 2,000 | mA |
| Reverse Voltage | V_R | 5 | V |
| Power Dissipation | P _D | 2,000 | mW |
| Operating Temperature | Topr | -30 ~ +85 | $^{\circ}\mathbb{C}$ |
| Storage Temperature | Tstg | -40~ +100 | $^{\circ}\!\mathbb{C}$ |
| Manual Soldering Temperature | Tsol | 260°C/5sec | 1 |

(Ta=25℃)



■Electrical -Optical Characteristics (Ta=25°C)

| Item | Symbol | Condition | Min. | Тур. | Max. | Unit |
|----------------------|------------------|-----------------------|------|------|------|-------|
| DC Forward Voltage*1 | V_{F} | I _F =700mA | - | 1.6 | 2.0 | V |
| DC Reverse Current | I_R | V _R =5V | - | - | 10 | μΑ |
| Peak Wavelength*2 | $\lambda_{ m P}$ | I _F =700mA | - | 940 | - | |
| Radiant Intensity*3 | Ie | I _F =700mA | 50 | 68 | - | mW/Sr |
| Radiant Power*4 | Po | I _F =350mA | 60 | 75 | - | mW |
| | | I _F =700mA | 120 | 150 | - | |
| 50% Power Angle | 2θ1/2 | I _F =700mA | - | 140 | - | deg |

^{*1} Tolerance of measurements of forward voltage is $\pm 0.1 \text{V}$

Note: Don't drive at rated current more than 5s without heat sink for Xeon 2 emitter series.

CNAS (1AB) ISO 9001: 2008







^{*2} Tolerance of measurements of Peak wavelength is ± 1 nm

^{*3} Tolerance of measurements of Radiant Intensity is $\pm 15\%$

^{*3} Tolerance of measurements of Radiant Power is +15%



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■ Soldering Heat Reliability:

Reflow soldering Profile

- · Reflow soldering should not be done more than two times.
- · When soldering, do not put stress on the LEDs during heating.
- · After soldering, do not warp the circuit board.
- · Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,

characteristics of the LEDs will or will not be damaged by repairing.

| Solder | | | |
|--|--|--|--|
| Average ramp-up rate = 3°C/sec. max. | | | |
| Preheat temperature: 150°~180°C | | | |
| Preheat time = 120 sec. max. | | | |
| Ramp-down rate = 6° C/sec. max. | | | |
| Peak temperature = 220°C max. | | | |
| Time within 3°C of actual | | | |
| peak temperature = 25 sec. max. | | | |
| Duration above 200°C is 40 sec. max. | | | |

